



Click [here](#) for the 3D model.

Dimensions

Chip Size	2824
L	7.1mm +/-0.4mm
W	6.1mm +/-0.4mm
T	2.5mm +/-0.20mm
B	1.27mm +/-0.4mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	300

General Information

Series	SMD Auto COG HV
Style	SMD Chip
Description	SMD, MLCC, Ultra-Stable, Low Loss, High Voltage, Automotive Grade
Features	Ultra-Stable, Low Loss, Automotive Grade
RoHS	Yes
Termination	Tin
Marking	No
Qualifications	AEC-Q200
AEC-Q200	Yes
Component Weight	540 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	0.056 uF
Measurement Condition	1kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	17.8571 GOhms